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一、BGA Rework station picture.

二、LV-08 BGA Rework station introduction：

- The machine adopts touch screen man-machine interface, heating time, heating temperature, heating speed, cooling time, advance alarm, vacuum time, etc. are all set in the touch screen, the operation is intuitive, simple and easy to get started；
- The product red heating tube using imported carbon fiber heating wire heating, heating fast and local temperature can be synchronized, PCB motherboard will not be deformed due to the temperature difference between hot and cold lead to welding defects, the glass is made of German Schott microcrystalline glass, high temperature 1200 ℃.
- This machine adopts Japan imported Panasonic PLC and Dalian Technology temperature control module independent control, real-time display of seven temperature curves, four independent temperature measurement interface, can be for the chip more than one point of accurate temperature judgment, so as to ensure that the chip welding yield；
- Three temperature zones independent heating, each temperature zone can be set independently of the heating temperature, heating time, heating slope; 10 heating temperature segments, simulating the 10-temperature reflow soldering heating mode, fully guarantee the welding effect of the BGA chip as well as welding quality.
- This machine is equipped with automatic feeding, sucking and discharging functions; it can automatically identify the center position of the chip when aligning, and the alignment lens can be moved backward and forward, left and right at any position when aligning, so as to prevent alignment dead ends.
- Multi-functional mode selection, there are [welding, removal, mounting, semi-automatic] four modes, automatic and semi-automatic functions can be realized, to better meet the multiple needs of different products；
- Using high-precision K-type thermocouples imported from the USA with closed-loop control, combined with our unique heating method, ensures that the welding temperature difference is within ±1° C.。
- The machine is equipped with an imported optical alignment system and a 15-inch high-definition display. It uses a high-precision micrometer for X/Y/R axis adjustments, ensuring alignment accuracy is controlled within 0.01mm.
- To ensure precise alignment, the upper heating head and placement head are integrated into one design. The machine is supplied with a variety of BGA heating nozzles to better meet the needs of different chips. The heating nozzles are easy to replace, and special requirements can be customized.
- High automation and precision completely eliminate human error. It delivers optimal results for lead-free processes and the rework of components like double-layer BGA, QFN, QFP, capacitors, resistors, and other components.

三、Technical Parameters:

Total Power	6800W
Upper Heating Power	1200W
Lower Heating Power	1200W
Lower Infrared Heating Power	4000W（2000Wcontrolled）
Other Power	400W
Power Supply	Single Phase AC 220V ±10 50Hz
Positioning Method	Optical lens + V-shaped slot + laser positioning light for quick positioning.
Temperature Control	High-precision K-type thermocouples (Ksensor) with closed-loop control, independent temperature measurement for upper and lower zones.Temperature Accuracy: ±1° C；
Electrical Components	High-sensitivity touchscreen + temperature control module + PLC + servo motor + stepper driver
Max PCB Size	590×460mm
Min PCB Size	10×10mm
Temperature Measurement Ports Pcs	4pcs
Chip Magnification	1-200 times
PCB Thickness	0.5-8mm
Applicable Chip Sizes	0.3*0.6mm-80*80mm
Min Chip Pitch	0.15mm
Maximum Mounting Weight	500G
Mounting Accuracy	±0.01mm
Dimensions	L750×W735×H935mm
Optical Alignment Lens	Electrically driven, adjustable for forward, backward, left, and right movement, eliminating alignment blind spots
Machine Weight	Net weight approximately 110kg